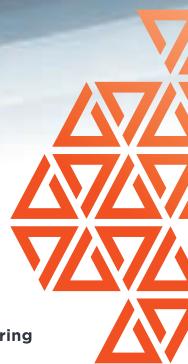


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SEMICON China and FPD China 2018 再相聚

March 14-16, 2018 SNEIC, Shanghai, China
OSA: 展位预定请到 Hall W1-1181

展览开放时间 Exposition Hours

星期二 3月14日 Tuesday March 14 09:00-17:00
星期三 3月15日 Wednesday March 15 09:00-17:00
星期四 3月16日 Thursday March 16 09:00-16:00

展览地址 Venue Address

上海新国际博览中心 上海市浦东新区龙阳路2345号
Shanghai New International Expo Centre No. 2345 Longyang Rd,
Pudong, Shanghai, China

联系方式 Contact

SEMI China
上海市浦东新区张东路1158号2号楼803室 (邮编 : 201203)
Tel: +86.21.6027.8500
Fax: +86.21.6027.8511
Email: semiconchina@semi.org

* Agenda is subject to change 最新活动议程以现场为准。



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观众手册 VISITOR GUIDE

2017年3月14日-16日 上海新国际博览中心

March 14-16, 2017 SNEIC, Shanghai

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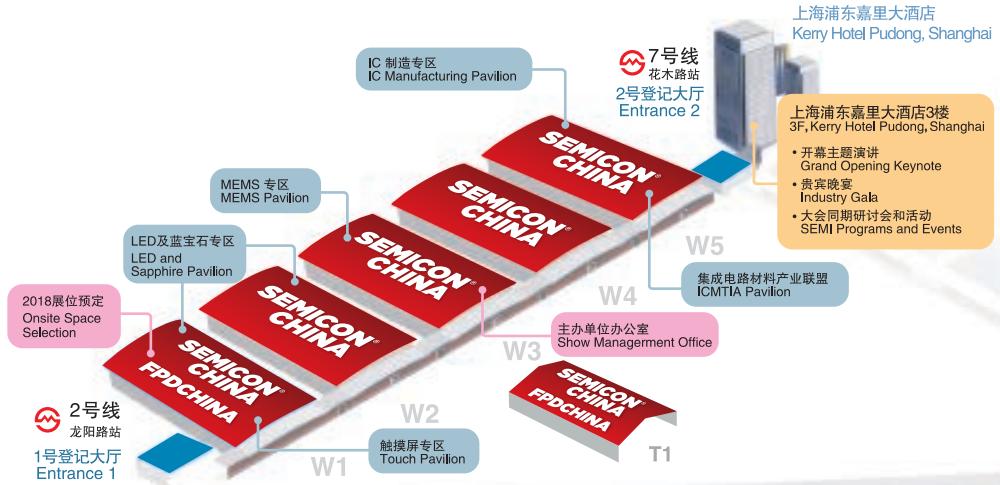
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FPD CHINA

欢迎致辞	P1
Welcome Message		
开幕主题演讲	P3
Grand Opening Keynote		
产业与技术投资论坛-中国2017	P4
Tech Investment Forum-China 2017		
SEMICON China 2017 同期研讨会	P5
SEMICON China 2017 Sessions/ Events		
2017中国显示大会—新兴显示论坛	P13
2017 China Display Conference - Emerging Display Forum		
同期活动一览表	P15
Events At-a-glance		
SEMICON China 2017 展商列表	P18
SEMICON China 2017 Exhibitor List		
FPD China 2017 展商列表	P23
FPD China 2017 Exhibitor List		
展馆平面图	P24
Floor Plan		
中国国际半导体技术大会 2017	P35
CSTIC2017		

展馆分布图

Pavilion Map



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欢迎致辞

欢迎来到SEMICON China 和FPD China 2017国际半导体展，见证全球半导体业界连续六年规格最高、规模最大的“嘉年华”！今年的SEMICON China展览面积达60,000多平方米，近900家参展商在3000个展位上与逾6万名专业观众互动，第29届SEMICON China必将再创辉煌！六大主题展区也更具特色和针对性，逾二十场同期会议更是把产业界的交流推向新的高度。这是一个中国主要芯片制造商、封测企业和来自全球设备、材料供应商携手合作的产业盛宴！



今年的开幕主题演讲汇集了中国及全球顶级行业领袖：中国大陆规模最大、技术最先进集成电路制造商中芯国际董事长周子学、全球领先的半导体制造设备和服务供应商泛林集团（Lam Research）总裁兼首席执行官Martin Anstice、ASML总裁兼首席执行官Peter Wennink、全球最大的芯片制造商Intel副总裁何军、东电电子首席技术官Sekiguchi Akihisa、以及全球最大半导体封测商日月光集团营运长兼董事吴田玉将在开幕主题演讲中畅谈产业发展愿景和计划，全球领先的微电子领域独立研究中心imec总裁和首席执行官Luc Van den hove也将在开幕主题演讲中分享全球产业发展趋势，这是中国半导体产业融入国际生态圈而开始的高端互动。

2016年全球半导体产业继续深度整合，随着中国半导体各路资本的逐步到位，资本市场的投资并购也继续升温。“产业与技术投资论坛 – 中国2017”集聚了国家大基金、各地IC产业基金、全球领先投资机构的掌门人。为了进一步覆盖大半导体完整产业链，SEMICON China 今年将首次举办“智能汽车电子论坛”、“智能制造论坛”以及“绿色厂房科技论坛”。其它各具特色的同期技术论坛还包括：“做大做强中国集成电路产业链”、“中国存储器产业发展论坛”、“功率及化合物半导体论坛”、“MSIG亚洲论坛2017”、“2017中国显示大会–新兴显示论坛”。这些结合中国特色、由全球市场领导型公司担当演讲嘉宾的技术论坛，期待您亲身体验、参与其中。

SEMICON China, FPD China 的参展商覆盖了半导体制造全产业链。绝大部分中国芯片制造企业和全球封测龙头企业，与来自全球的设备材料供应商一起，为我们呈现了完整的半导体制造生态体系。在中国半导体产业高速发展的当下，SEMI中国将全力在快速变化的中国半导体产业链中，利用SEMI国际化、专业化、本土化的服务平台为会员提供更多的价值，引进先进的技术、人才，提升中国企业国际竞争力，同时帮助优秀的中国本土公司走向国际市场，积极扮演好我们沟通桥梁的角色，成为实现中国半导体梦想的合作伙伴！

居龙

SEMI全球副总裁、中国区总裁

Welcome Message

I would like to welcome you to SEMICON China and FPD China 2017, a most premier global semiconductor industry gathering, and the world's largest Semiconductor trade show for the past six years! This year's SEMICON China covering an area of 60,000 square meters, nearly 900 exhibitors, 3,000 booths and expected 60,000 visitors. This 29th SEMICON China will bring you a wonderful experience! Many theme pavilions at the exposition demonstrate the vitality of the industry. The 20+ concurrent conferences and programs bring the global industry knowledge sharing to a new level. This is an industry gathering with Chinese major chip manufacturers, packaging and testing companies and global equipment and material suppliers together!

The Grand Opening Keynote of SEMICON China will be delivered by world-class industry leaders: Chairman of the Board, SMIC, President and CEO of Lam Research, VP of Intel, Director & COO of ASE, President and CEO of ASML, CTO of Tokyo Electron, President and CEO of imec, who will explore the global business & technology trend, market opportunities, and share their ideas supporting China's semiconductor industry development.

As global semiconductor industry continues its integration trend, China is embarking on a new round of expansion and investment. In “Tech Investment Forum - China 2017”, leaders of China's IC Investment Fund and leading global investment institutions will discuss investment hot topics. Three new forums, “Smart Automotive Forum”, “Smart Manufacturing Forum” and “Green High-Tech Facility Forum” will be held for the first time in SEMICON China this year, further extending SEMI's coverage of the IC supply chain. Other concurrent technology conferences with exciting topics include “Build China's IC Ecosystem”, “China Memory Strategic Forum”, “Power & Compound Semiconductor Forum”, “MEMS & Sensors Industry Group Conference Asia 2017” and “2017 China Display Conference - Emerging Display Forum”. These conferences provide ideal platform for the leaders and professionals of global semiconductor industry to gather, explore industrial development, share their vision, and work together to grow the industry!

Exhibitors of SEMICON China and FPD China 2017 cover the full industry chain of semiconductor manufacturing. Almost all China's leading device makers, and global top packaging houses exhibit at SEMICON China. Together with their global equipment and materials suppliers, a full ecosystem of semiconductor manufacturing is presented. With the rapid development of China semiconductor industry, SEMI will leverage its international, professional and local service platform to provide more value for the SEMI members, introduce advanced technology, talents, enhance the international competitiveness of Chinese enterprises, help local companies to enter the international market during the fast changing of Chinese semiconductor industry chain. SEMICON China and FPD China 2017 will help your business by CONNECTING China and global semiconductor industries! SEMI China will serve as the ideal partner in the development of China semiconductor industry, and its integration in the global semiconductor ecosystem.

Sincerely

Lung Chu

President, SEMI China

开幕主题演讲 Grand Opening Keynote

 现场提供同声传译 Chinese and English Simultaneous Interpretation will be provided

开幕主题演讲汇集全球顶级行业领袖，是SEMICON China 这一全球最大规模半导体年度盛会中不容错过的部分，是了解全球产业格局、前沿技术与市场走势，分享全球业界领袖智慧和视野，并与他们面对面交流的难得机会。

会议赞助:



Zhou Zixue
中国半导体行业协会理事长
中芯国际董事长, 执行董事
Chairman, CSIA
Chairman of the Board, SMIC



Martin Anstice
泛林集团总裁兼首席执行官
President and CEO
Lam Research



Jun He
英特尔副总裁
VP
Intel



Tien Wu
日月光集团营运长暨董事
Director & COO
Advanced Semiconductor Engineering, Inc.
(ASE Group)



Peter Wennink
阿斯麦光刻设备有限公司总裁
兼首席执行官
President and CEO
ASML



Sekiguchi Akihisa
东电电子首席技术官
CTO
Tokyo Electron



Luc Van den hove
imec 总裁兼首席执行官
President and CEO
imec

日期 Date: 2017年3月14日 星期二

Tuesday, March 14, 2017

时间 Time: 12:30 - 16:35

地点 Venue: 上海浦东嘉里大酒店, 上海大宴会厅1
Grand Shanghai Ballroom 1,
Kerry Hotel Pudong, Shanghai

产业与技术投资论坛—中国2017 Tech Investment Forum -China 2017

 现场提供同声传译 Chinese and English Simultaneous Interpretation will be provided

日期 Date: 2017年3月15日 星期三

Wednesday, March 15, 2017

时间 Time: 09:00 - 16:35

地点 Venue: 上海浦东嘉里大酒店, 浦东大宴会厅5+6+7, Kerry Hotel Pudong, Shanghai



2016年全球半导体产业继续深度整合，大规模并购不断。在这样的大背景下，随着中国半导体各路资本的逐步到位，产业新生力量不断涌现，资本市场的投资并购也继续升温。

SEMICON投资论坛是SEMI中国旗下的产业与技术投资峰会，汇聚国内外产业与投资领袖，为全球产业同仁和投资精英分享全球集成电路产业的市场趋势，并分享投资并购重组等方面的真实灼见，是广受认可的半导体产业战略发展与投资合作的交流平台。

此次论坛，集聚国家大基金、各地 IC 产业基金、全球领先投资机构负责人，共同剖析中国半导体新政之后的新机遇，探讨不容错过地投资、兼并以及半导体产业应用如人工智能的最新趋势等热点话题。

赞助商: 



Ding Wenwu
国开金融有限责任公司总裁
中国光大圆融
芯片联盟理事长
President, China National IC Industry Investment Fund
Chairman, China High-end Integrated Circuits Alliance



Liang Sheng
北京经济技术开发区
管委会主任
Director of Management Committee, BDA



Wei Shaojun
清华大学微电子学研究所所长
Director, Institute of Microelectronics, Tsinghua University



Ye Tianchun
中国科学院微电子
研究所所长
Director, Institute of Microelectronics Chinese Academy of Sciences



Handel Jones
International Business Strategies
Strategies首席执行官
CEO, International Business Strategies, Inc.



Shen Weiguo
上海集成电路产业投资基金董事长,
上海科技创业投资(集团)
有限公司董事长
Chairman of the Board,
Shanghai Integrated Circuit Industry Investment Fund
Chairman of the Board,
Shanghai S&T Investment Co., Ltd.



Sun Yuwang
中芯聚源股权投资管理
(上海)有限公司总裁
President, China Fortune-Tech Capital Co., Ltd.



Wu Ping
武岳峰资本创始合伙人
President, Summitview Capital



Wang Xiaobo
北京亦庄国际投资发展
有限公司总经理
General Manager,
Beijing E-Town International Investment & Development Co., Ltd.



Donald Lu
高盛公司董事总经理
Managing Director,
Goldman Sachs



Christopher Thomas
麦肯锡公司全球董事合伙人
全球数字化与先进技术战略业
务负责人及亚洲半导体业务负责人
Managing Partner,
Global Digital and Advanced Technology
Strategy Practice &
Asia Semiconductor
Practice, McKinsey &
Company, Inc.



Hing Wong
华登国际董事总经理
Managing Director,
Walden International



Allen Wu
ARM大中华区全球执行
副总裁兼大中华区总裁
EVP and President, ARM Greater China



Guo Dong
华为业务发展总监
Director of Business Development, Huawei

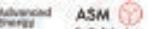


Chen Datong
北京清华丘山资本投资
咨询有限公司董事总经理
Managing Director,
WestSummit Capital Management
Charlie Chan
摩根士丹利中国执行董事
Executive Director,
Morgan Stanley

做大做强中国集成电路产业链 Build China's IC Ecosystem

日期 Date: 2017年3月15日 星期三
Wednesday, March 15, 2017
时间 Time: 09:00 ~ 16:50
地点 Venue: 上海浦东嘉里大酒店, 浦东大宴会厅1+2+3
Pudong Ballroom 1+2+3,
Kerry Hotel Pudong, Shanghai

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做大做强中国集成电路产业链—先进制造与封测

Build China's IC Ecosystem –
Advanced Manufacturing, Assembly & Test

主持人 Moderator:
Dr. Yifan Guo,
Vice President, ASE

09:00-09:05 欢迎致辞 Welcome speech
Richard Salsman
CFO and Vice President Operations, SEMI

09:05-09:30 Innovative 3D-SiP Package Technologies for More than Moore Era.
蓝章益 Albert Lan
Director, SPIL

09:30-09:55 Keynote Speech:
互利共赢 深化中国IC产业布局
雷海波 Haibo Lei
President, HLMC

09:55-10:20 国产处理器加速中国集成电路产业国际化进程
傅城 Frank Fu
兆芯, VP

10:20-10:45 Heterogenous Integration and miniaturization for IC package solutions
Dr. Jim Li
Sr. Director, Central Engineering Integration, ASE

10:45-11:10 Assembly Development for Advanced SIP Module
徐玉鹏 Yupeng Xu
VP of Engineering, ICPU of JCET

11:10-11:35 提升核心竞争力，做强中国集成电路产业链
Strengthening China's IC Ecosystem with Core Competitiveness
许天葵 Sunny Hui
SMIC, 全球市场部资深副总裁
Senior Vice President of Marketing, SMIC

11:35-12:00 Advance Package
樊俊豪 Fan Chun Ho
Vice president, ASM

做大做强中国集成电路产业链 – 装备和材料

Build China's IC Ecosystem –
Equipment and Material

主持人 Moderator:
Michael Young
GM, APAC Sales, Marketing & Service, AE

13:00-13:30 Maximizing fab profitability through lifecycle services
Mike McDonald
Vice President, Global Service, AE

13:30-14:00 Keynote Speech:
高端装备国产化，小集成铸就大时代
赵晋荣 Jinrong Zhao
北方华创科技集团股份有限公司, 总裁

14:00-14:30 The back-end market analysis and TEL's activity
Mr. Kawauchi Takuo
Region Strategy Division, TEL

14:30-15:00 Thomas Bondur
Corporate Vice President, Advanced Packaging, MEMS and IoT Business Group, Lam Research

15:00-15:20 Break

15:20-15:50 The Memory Evolution: 2D to 3D and Beyond
Er-Xuan Ping
Managing Director, Office of the Chief Technology Officer, Applied Materials, Inc.

15:50-16:20 Enable IC breakthroughs with MKS Instruments surrounding chambers
Wei Shao
General Manager, MKS Instruments (Shanghai) Ltd.

16:20-16:50 Build cost advantage by right capital equipment purchasing strategy
商海涵 Jonathan Shang
盈球半导体科技（上海）有限公司, 总经理
General Manager, SurplusGLOBAL China, Inc., SurplusGLOBAL

connect

智能汽车电子论坛 Smart Automotive Forum

日期 Date: 2017年3月16日 星期四
Thursday, March 16, 2017

时间 Time: 08:30 ~ 12:00

地点 Venue: 上海浦东嘉里大酒店, 浦东大宴会厅1+2+3
Pudong Ballroom 1+2+3,
Kerry Hotel Pudong, Shanghai

钻石级赞助商:

赞助商: 日月光集团

精品精密
Siliconware

08:30-09:00 来宾登记
Registration

主持人 Moderator:

彭亮 Liang Peng

华美半导体协会 (CASPA), 执行顾问
Executive of Advisory Board, Chinese American Semiconductor Professional Association (CASPA)

09:00-09:05 欢迎致辞 Welcome

Peter Gillespie
CMO, SEMI

09:05-09:30 推动工程灵活性的第三波冲击
The 3rd wave of disruption driving agility of engineering
Russell Lee

明导 (上海) 电子科技有限公司, 资深总监
Senior Director, Mentor Graphics

09:30-09:55 智能汽车及其相关电子产品的未来趋势
Future trends of smart car & associated electronics
贺柏睿 博士

Dr. Patrick Leinenbach

博世汽车电子中国区总裁, 博世汽车部件 (苏州) 有限公司总经理
Regional President of Bosch Automotive Electronics China, GM of Bosch Automotive Products (Suzhou) Co., Ltd.

09:55-10:20 恩智浦安全智能驾驶与智能交通解决方案
NXP secure ADAS&V2X solution
吕浩

Martin Lu

恩智浦半导体, 汽车电子产品应用部, 总监
Director, Automotive Product Application, NXP Semiconductor Ltd

10:20-10:45 NVIDIA 自动驾驶
NVIDIA self-driving solution

陈曦 Stephen Chen
NVIDIA, 高级业务发展总监
Senior Director of Business Development, NVIDIA

10:45-11:10 用于电动汽车逆变器系统的IGBT套件解决方案
Renesas IGBT kit solution for EV inverter systems

Masahige Tada
瑞萨电子, 副总裁, 汽车电子控制模拟与电源器件解决方案业务部部长
Vice President, Head of Automotive Analog & Power Solution Division, 1st Solution Business Unit, Renesas Electronics Corporation

11:10-11:35 电动汽车与智能化驱动下的车用半导体技术
Automotive semiconductor technologies under new energy and Intelligent trend

冯奇 博士
Dr. Qi Feng
上汽集团, 前瞻技术研究部总监
Director, Research & Advanced Technology, SAIC MOTOR Corporation Limited

11:35-12:00 汽车电子封装解决方案
Packaging solutions for Automotive

沈政昌
Allen Shen
日月光集团, 汽车电子工艺工程部总监
Director, Automotive Process Engineering, ASE Group

功率及化合物半导体论坛

Power & Compound Semiconductor Forum

 现场提供同声传译 Chinese and English Simultaneous Interpretation will be provided

Day1-Mar.15, 2017

*Session 1: LED及光电 (原LED China 论坛)
LED & Optoelectronics (Previously known LED China Conference)

08:30-09:15	注册 Registration	日期 Date: 2017年3月15-16日 星期三-星期四 Wednesday-Thursday, March 15-16, 2017 时间 Time: 08:30 - 17:00
09:15-09:20	欢迎致辞 Welcome Remark	地点 Venue: 上海浦东嘉里大酒店, 浦东宴会厅4 Pudong Ballroom 4, Kerry Hotel Pudong, Shanghai
09:20-09:50	主旨演讲 Keynote Speech 王敏 Min Wang 晶能光电首席执行官 CEO, Lattice Power Corporation	电子股份有限公司, CEO CEO of APT Electronics, Co-Chair of SEMI China LED Advisory Committee
09:50-10:15	从制造角度看氮化镓激光 Gallium Nitride Lasers from a Manufacturing Perspective Christian Schmid 欧司朗光电子半导体, 前端技术项目经理 Project Manager, Osram Opto Semiconductors	13:30-14:00 硅基氮化镓——一个正在走向成熟的颠覆性半导体技术 GaN on Si - a truly revolutionary semiconductor technology matures Dr. Markus Behet Chief Marketing Officer, EpiGaN
10:15-10:40	次世代显示技术PixelLED的发展 The Development of Next Generation PixelLED Display Technology 李允立 Charles Li 臻創科技, 首席执行官 CEO, PlayNitride	14:00-14:30 用于高效电力电子半导体器件的GaN和SiC外延生产技术的进一步发展 Further advances in GaN and SiC epitaxial production technologies for efficient power semiconductor devices Dr. Frank Wischmeyer 德国爱思强股份有限公司, 电力电子器件副总裁 Vice President Power Electronics, AIXTRON SE
10:40-11:05	用于PSS AOI的光学镜头的设计及评估 Design and evaluation of optical lens for PSS AOI System 马铁中 Aris MA 昂坤视觉(北京)科技有限公司, 首席执行官 CEO, BeiOptics Technology Co. Ltd.	14:30-15:00 对宽禁带功率器件的期望 Expectation for WBG power devices Masakatsu Hoshi 日产汽车, 高级工程师 Senior Engineer, Nissan Motor Co., Ltd
11:05-11:30	深紫外LED氮化铝衬底单晶生长技术最新进展及未来面临的挑战 Recent progress and future prospects on Bulk AlN crystal growth for Deep UV-LED applications 吴亮 Liang Wu 协鑫, 首席工程师 Chief Engineer, GCL	15:00-15:30 高密度ICP刻蚀机在新型功率器件制造中的应用 The application of high density ICP etch equipment in new power devices manufacture 杨盟 Yang Meng 北京北方华创微电子装备有限公司, 刻蚀事业部 副总经理 Product Director and Deputy GM of Etch Product Division, Beijing NAURA Microelectronics Equipment Co., Ltd.
11:30-12:00	高效率氮化物LED芯片市场及技术发展趋势 Market and Research Trends for High Efficiency GaN based LEDs 王江波 Jiangbo Wang 华灿光电股份有限公司, 副总裁 Vice President, HC SemiTek Corporation	15:30-16:00 华功半导体GaN功率电子器件的产业化进程 Efforts towards GaN power FETs in Sinopower Semiconductor 刘扬 Yang Liu 江苏华功半导体有限公司, 技术副总裁 Vice president, SINOPOWER SEMICONDUCTOR CO., LTD.
12:00-13:30	休息 Break	16:00-16:30 单片MOCVD技术发展推动功率&微波电子器件的商业化 Power & RF Electronics commercialization through MOCVD advancements from Single Wafer Reactor technology Somit Joshi Sr. Director of Marketing in Veeco
	*Session 2: 宽禁带半导体电力电子 Wide Band Gap Power Electronics Session 2 主持人 Moderator: 肖国伟 David Xiao SEMI中国LED顾问委员会Co-Chair, 广东晶科	16:30-17:00 用于下一代电源转换的GaN E-HEMT GaN E-HEMT for the next era of power conversion Charles Ballely Senior Director, Asia, Sales, Mktg, & Apps, GaN Systems Inc.

connect

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鸣谢:



Day2-Mar.16, 2017

*Session 3: 化合物半导体及通讯
Compound Semiconductor in Communications

Session 3 主持人 Moderator :
张乃千 Naqian Zhang
苏州能讯高能半导体有限公司, 总裁
President, Dynax Semiconductor, Inc.

09:25-09:30 欢迎致辞
Welcome Remark

09:30-09:55 无线通讯用六寸氮化镓HEMT量产技术
High volume 6" GaN/SiC HEMT technology for wireless communication applications
叶念慈 Tim Yeh
三安集成电路, 氮化镓技术开发处副总监
Director, GaN TD Division, SANAN IC

09:55-10:20 应用于移动通讯的高效高可靠氮化镓射频器件开发
Development of high efficient and high reliable GaN RF Device for Mobile Application
裴轶 Yi Pei
能讯高能半导体, 器件技术总监
Director of Device Technology, Dynax Semiconductor

10:20-10:45 稳懋半导体0.45/0.25 微米氮化镓高速电子元件之发展
Pure Play GaN HEMT 0.45/0.25-μm Technology Development for Wireless Application
林正国 C.K. Lin
稳懋半导体股份有限公司, 总监
Director, WIN Semiconductors Corp.

10:45-11:10 用于优化砷化镓、氮化镓器件的外延生长分析技术
GaAs and GaN based device optimization by advanced epitaxial growth analysis
Tom Thieme
Director Marketing and Sales, LayTec AG

11:10-11:35 SiGe BICMOS工艺技术的无线应用
SiGe BICMOS Process Technologies for Wireless Applications
Edward Preisler
Towerjazz

11:35-12:00 A Multipurpose Millimeter Wave High Power and Low Noise GaN/Si Process for High Frequency Transmit-Receive MMICs
LEBLANC Remy
Director, Product Development, OMMIC

12:00-13:30 休息 Break

13:30-14:00 氮化镓和相关材料的射频和电力电子应用
GaN and Related Materials for RF and Power Electronics Applications
Wayne Johnson
Vice President & Head of Power Business Unit, IQE

*Session 4: 新型功率器件
Emerging Power Device Technology

Session 4 主持人 Moderator :
杨继业 Jiye Yang
华虹宏力集成一部总监
Senior director, TD Integration Division I, HHGrace

14:00-14:30 高功率应用对器件和封装技术的要求
Device and packaging technologies for demanding high power applications
Arnoft Kopta
Head of BiMOS R&D, ABB Switzerland Ltd, Semiconductors

14:30-15:00 碳化硅功率器件的发展和大规模生产的现状
Status of Development and Mass Production for SiC Power Device
金泽博 Hiroshi Kanazawa
Marketing Unit Manager, Showa Denko K.K.
昭和电工

15:00-15:30 功率器件的未来和半导体制造设备的启示
The Future of Power Devices and Implications for Semi Equipment
Durga Chaturvedula
Managing Director, 200mm Product Mgmt. & Technology, Applied Materials

15:30-16:00 电力系统电力电子器件需求、现状及发展趋势
Demand, Status and Development Trend for Power Electronic Device
邱宇峰 Yufeng Qiu
Party group secretary, State Grid, Global Energy Interconnection Research Institute
全球能源互联网研究院, 国家电网, 党组书记

16:00-16:30 硅、碳化硅和氮化镓功率器件的薄膜工艺
Thin Film Processes for Si, SiC and GaN Power Devices
Hans Auer
Senior Product Marketing Manager, Evatec

16:30-17:00 闭幕演讲 Closing Keynote
新型结构晶体管及新一代功率芯片的研究
Research of Power Semiconductor Devices with Novel Structures
王鹏飞 Pengfei Wang
东微半导体, 首席技术官
CTO, Oriental Semiconductor

MSIG亚洲论坛2017

MEMS & Sensors Industry Group Conference Asia 2017

日期 Date: 2017年3月16日 星期四
 Thursday, March 16, 2017
 时间 Time: 08:00 - 17:00
 地点 Venue: 上海浦东嘉里大酒店, 浦东大宴会厅5+6+7,
 Pudong Ballroom 5+6+7,
 Kerry Hotel Pudong, Shanghai



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08:00-09:00	注册 Registration	14:15-14:45	MEMS Sensors and the Supply Chain: Improving Time to Market Roc Blumenthal Senior Director, Vertical Marketing, SMIC
09:00-09:30	开幕欢迎词 Welcome and Introduction Karen Lightman Vice President, MEMS & Sensors Industry Group	14:45-15:15	CMP process stability and tool capacity improvement with Mirra heads Yanghua He Senior Process Development Engineer, Qorvo
09:30-10:15	An IoT startup's perspective on business applications of MEMS and sensor Vivi Zhang Head of Global Strategy, Sensoro	15:15-15:45	茶歇 Coffee / Tea Break
10:15-10:45	Sensor Platform Value, Today, Tomorrow and Beyond... Behrooz Abdi President and CEO, InvenSense	15:45-16:45	圆桌讨论 Panel: Future of MEMS and Sensors in IoT and Mobile 主持人 Moderator: Sean Ding, Director of Sensing, Chief Scientist, Huawei
10:45-11:15	茶歇 Coffee/Tea Break		论坛嘉宾 Panelists: Leopold Beer, Regional President Asia Pacific, Bosch Sensortec
11:15-11:45	Smart Parking – How sensors and connectivity save money, time and our environment Becky Oh President and CEO, PNI Sensor		Ben Lee, CEO, mCube
11:45-12:15	Translating Flexible Hybrid/Printed Electronics into Innovative Human-Machine Interface (HMI) and IoT Solutions Albert Lu CTO, Interlink Electronics		Becky Oh, President and CEO, PNI Sensor
12:15-13:45	午餐自理 Lunch on own	16:45-17:00	闭幕总结 Session Summary Karen Lightman Vice President, MEMS & Sensors Industry Group
13:45-14:15	How Entertainment, Automotive, and Voice Will Fuel New Demand for MEMS and Sensors David Allan President, Virtuix Inc.		闭幕招待会 Evening Reception
		17:00	

绿色厂区科技论坛

Green High-Tech Facility Forum

(会议期间场馆提供WIFI服务)

主办: semir

协办: simtec

蓝宝石级赞助商:

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09:00-09:20 **注册 Registration**

09:20-09:25 **欢迎致辞 Welcome Speech**

Kary Chien
中芯国际
SMIC

09:25-09:50 **Sustainable, Cost-Effective Semiconductor Facility Design Trends**

Hartmut Schneider
Vice President, M+W

09:50-10:15 **高等级晶圆厂净化及气态污染物控制 AMC control in critical minienvironment**

何娜娜 Nana He
康斐尔, 分子过滤产品经理
Molecular Filtration Product Manager, Camfil

10:15-10:40 **中芯国际 绿色厂区及厂区系统设计 SMIC Green FAB and Facility design**

姜镭 Radium Jiang
中芯国际北京, 厂务总监
Facility Director, SMIC Beijing

10:40-11:00 Break

11:00-11:25 **Energy conservation and PFC emissions control in point of use wet-thermal-wet abatement system**

胡石政 博士 Dr. Shih-Cheng Hu
台湾科技大学, 中华洁淨协会理事長, 潔淨技术研發中心主任
Director, National Taipei University of Technology

11:25-11:50 **项目前期工作和投资管理要点 Key points of early-stage work and cost management in construction**

鲍伟忠 Weizhong Bao
上海申元工程投资咨询有限公司, 总工程师
Chief Engineer, Shanghai Shenyuan Property Consultants Co.,Ltd

展位号 : W3 3459

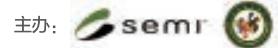


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智能制造论坛 Smart Manufacturing Forum

(会议期间场馆提供WIFI服务)



协办:



赞助商:



13:00-13:30 注册 Registration

13:30-13:35 欢迎致辞 Welcome Speech

Rich Salsman
SEMI, 全球副总裁
Global VP, SEMI

13:35-14:00 工业4.0下半导体行业的智能化设计与制造
The power of intelligent design and manufacturing in semiconductor industry

张治平 Jason CHANG
西门子, 半导体/医疗器械及生命科学/消费品及零售
业, 技术总监
Technical Head of SEMI, Medical Device & Life
Science, CP&R, Siemens

14:00-14:25 Applying the 10 Fundamental Truths of Process Control to Smart Manufacturing Solutions

Dr. Douglas Sutherland
KLA-Tencor, 首席科学家
Principal Scientist, KLA-Tencor

14:25-14:50 认知制造 Cognitive Manufacturing

日期 Date: 2017年3月15日 星期三

Wednesday, March 15, 2017

时间 Time: 13:00 - 16:30

地点 Venue: 上海新国际博览中心W3馆, M10会议室
Meeting Room 10, Hall W3,
Shanghai New International Expo Centre

Andrew Vogel
IBM大中华区行业解决方案及业务拓展部总经理
General Manager, GCG Electronics Industry Solutions and Business Development Department, IBM

Lights OFF Manufacturing

Betty Wu
闪迪, 副总裁, Vice President of Operation, SanDisk

智慧制造的资源整合与共享

Resource integration and sharing for smart manufacturing
高腾 博士 Dr. Teng GAO
上海微技术国际合作中心, 总裁
President, Shanghai International Micro-Tech Affiliation Center (SIMTAC)

智能制造在无锡英飞凌的应用

The Application of Smart Manufacturing in Infineon WuXi

祁尔莎丹
英飞凌科技(无锡), 工厂集成经理
Factory Integration Manager, Infineon

connect

中国存储器产业发展论坛 China Memory Strategic Forum

日期 Date: 2017年3月14日 星期二

Tuesday, March 14, 2017

时间 Time: 08:30 - 11:45

地点 Venue: 上海浦东嘉里大酒店, 浦东宴会厅1+2+3
Pudong Ballroom 1+2+3,
Kerry Hotel Pudong, Shanghai

主办: 协办: 赞助商:

鸣谢:

08:30-09:00 注册 Registration

09:00-09:03 Welcome Speech
Peter Gillespie
SEMI, 全球副总裁
SEMI, Global VP

09:03-09:10 开场介绍:
储存器最新发展简介
Opening Introduction:
The Latest Development of Memory Industry
主持人 Moderator:
彭安 Andrew Peng
CSO and Vice President of Business Development, Tong Fu Microelectronics Co., Ltd; Deputy to JEDEC Chairman

09:10-09:40 主题演讲:
美光科技—存储器创新的历史与未来
Keynote speaking:
A History and Future of Memory Innovation
Dean A. Klein
VP Advanced Memory Solutions, Micron Technology, Inc.

09:40-10:05 Nanosecond scale storage: ultrafast SSDs and persistent memory applications of emerging NVMe
Zvonimir Bandic
Sr. Director, Next Generation Platform Technologies, Western Digital Corporation

10:05-10:30 Fabless Specialty Memory: A Growing Sector with a Vibrant Eco-System
曹堪宇 Mark Cao
Vice President, Strategic Marketing, Gigadevice Semiconductor (Beijing) Inc.

10:30-10:55 Advanced Packaging for Flash Memory
梁新夫 Steve Liang
CTO, Jiangsu Changjiang Electronics Technology Co., Ltd

Critical challenges and solutions in 3D NAND volume manufacturing
Rich Wise
Technical Managing Director, Global Product Group, Lam Research Corporation

Memory Packaging Challenges for the New Era
E. Jan Vardaman
President of TechSearch International, Inc.

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- Marvell美满电子-出售新型的高品质半导体后道设备Eagle ETS-364, Advantest T2000, UltraFlex Tester, EO Laser打孔机等(中国, 台湾, 新加坡)
- Texas Instruments-出售200mm晶圆制造设备(中国)
- 全球知名半导体晶圆厂-出售整厂生产制造设备(日本)
- NEMOTEK Technolgie-出售优质200mm晶圆半导体前道及后道设备(摩洛哥)



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2017中国显示大会—新兴显示论坛

2017 China Display Conference - Emerging Display Forum

 现场提供同声传译 Chinese and English Simultaneous Interpretation will be provided

Some Distinguished Speakers 部分特邀演讲嘉宾



闫晓林



Susumu Ohi



Andreas Kreisel



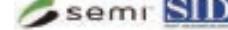
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Teruyuki Hayashi



张雪娜

主办:  

钻石级赞助商:



鸣谢:  

金牌赞助商:



特别支持:



09:00-09:25 注册 Registration

09:25-09:40 主持人 Moderator
严群 Frank Yan
SID会士,SID中国区总裁
SID Fellow, Director of SID China

开幕致辞 Opening remark
Peter Gillespie
CMO, SEMI

09:40-10:10 主旨演讲 Keynote Speech

闫晓林 Xiaolin Yan
CTO & Senior Vice President of TCL Group of China

10:10-10:40 Display Technology for Next Big Market

Dr. James Lee
Deputy Chief Engineer, TCL Corporate Research

10:40-11:10 Important Technologies of Ink Jet System for OLED Display Fabrication

Teruyuki Hayashi

11:10-11:40 Group Leader, Innovative Technology Planning Dept. TEL

TFT玻璃基板1.5um曝光分辨率工艺解决方案

Solution for 1.5um Resolution on TFT Plate

周畅 Chang Zhou
上海微电子产品总监
Product Director, SMEI

12:00-13:00 午间休息 Lunch Break

13:00-13:30 Micro-LED Displays

江红星 Hongxing Jinag
美国物理学会会士, 德克萨斯理工大学教授
Fellow of American Physical Society,
Professor of Texas Tech University

13:30-14:00 Micro-LED 显示技术的发展
Development of Micro-LED Display Technology

刘召军 Zhaojun Liu
中山大学教授
Professor, Sun Yat-sen University

日期 Date: 2017年3月15日 星期三

Wednesday, March 15, 2017

时间 Time: 09:00 - 16:40

地点 Venue: 上海新国际博览中心W2馆M9会议室
Meeting Room 9, 2nd Floor, Hall W2,
Shanghai New International Expo Centre

14:00-14:30 Next Generation Emissive Displays Enabled by Quantum Dots

罗忠升 Luo Zhongsheng
Nanosys大中华区总经理
General Manager, Greater China and Applications Engineering,Nanosys

14:30-14:50 显示测量技术的新趋势
New Trendy Displays Technology and Metrology

邵伟宇 Felix Shao
柯尼卡美能达应用技术总经理
Principal Technical application GM, Konica Minolta

14:50-15:10 Electro-Optical Testing of OLED Displays

Andreas Kreisel
Application VP, Instrument Systems GmbH

15:10-15:40 在线扫描电子显微镜技术加速高精尖面板产业良率提升

Accelerating Advanced Display Yield Ramps with Inline SEM Electron Beam Review

张雪娜 Xuena Zhang
应用材料高级技术经理
Senior Technical Manager, Applied Materials AKT Display Business Group

15:40-16:10 The Automotive Display Innovation

Susumu Ohi
天马微电子副总经理,天马PDB研究中心首席技术执行官
Vice President, CTO of PDB R&D Center,Tianma

16:10-16:40 USB Type-C Direct Drive TCON for Notebook and Monitors Connection

Adam Chen
硅谷数模半导体市场部高级总监
Senior Marketing Director, Analogix Semiconductor

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2017 Program and Events At a Glance
2017同期活动一览

投资论坛 INVESTMENT FORUM POWER&功率及化合物 COMPOUND FORUM

中国半导体产业 IC INDUSTRY FORUM EMERGING DISPLAY FORUM

MEMS & SENSORS MSIG 亚洲论坛 FORUM 汽车电子 AUTOMOTIVE FORUM

Sunday and Monday Mar 12-13 周日、周一 3月12-13日			
CHINA 中国半导体产业 IC INDUSTRY FORUM 08:45-17:30 中国国际半导体技术大会		China Semiconductor Technology International Conference 上海国际会议中心	
Tuesday Mar 14 周二 3月14日			
CHINA 中国半导体产业 IC INDUSTRY FORUM 09:00-12:00 中国存储器产业发展论坛		China Memory Strategic Forum Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Grand EVENTS 13:00-16:35 开幕主题演讲		Grand Opening Keynote Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Grand EVENTS 17:30-21:00 SEMI Industry Gala (By invitation)		SEMI Industry Gala (By invitation) Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Wednesday Mar 15 周三 3月15日			
CHINA 中国半导体产业 IC INDUSTRY FORUM 09:00-12:00 做大做强中国集成电路产业链 - 先进制造与封测		Build China's IC Ecosystem - Advanced Manufacturing, Assembly & Test 2017 China Display Conference - Emerging Display Forum Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
EMERGING DISPLAY FORUM 09:00-17:00 功率及化合物半导体论坛 (第一天)		2017 China Display Conference - Emerging Display Forum Power & Compound Semiconductor Forum (Day 1) Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
POWER&功率及化合物 COMPOUND FORUM 09:00-17:00 产业与技术创新论坛 - 中国 2017		Power & Compound Semiconductor Forum (Day 1) Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Investment FORUM 09:30-17:00 Tech Investment Forum - China 2017		Tech Investment Forum - China 2017 Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
CHINA 中国半导体产业 IC INDUSTRY FORUM 09:00-12:00 绿色厂房科技论坛		Green High-Tech Facility Forum Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
CHINA 中国半导体产业 IC INDUSTRY FORUM 13:30-17:00 智能制造论坛		Smart Manufacturing Forum Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
CHINA 中国半导体产业 IC INDUSTRY FORUM 13:00-17:00 设备和材料 - Equipment and Material		Build China's IC Ecosystem - Equipment and Material Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Grand EVENTS 17:30-21:00 China IC Night (By invitation)		China IC Night (By invitation) Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Thursday Mar 16 周四 3月16日			
汽车电子 AUTOMOTIVE FORUM 09:00-12:00 智能汽车电子论坛		Smart Automotive Forum Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
POWER&功率及化合物 COMPOUND FORUM 09:30-17:00 功率及化合物半导体论坛 (第二天)		Power & Compound Semiconductor Forum (Day 2) Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
MEMS & SENSORS MSIG 亚洲论坛 FORUM 09:00-17:00 MEMS & Sensors Industry Group Conference Asia 2017 MSIG 亚洲论坛 2017		MEMS & Sensors Industry Group Conference Asia 2017 Kerry Hotel Pudong, Shanghai 上海浦东嘉里大酒店	
Friday Mar 17 周五 3月17日			
Grand EVENTS 07:30-15:00 "芯片会" SEMICON China 高尔夫精英赛(特邀)		"芯片会" SEMICON China 高尔夫精英赛(特邀) Shanghai Sheshan International Golf Club 佘山高尔夫俱乐部	

DAIHEN

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FPD China 2017展览通知



敬启，在此早春之际，恭祝贵公司日益繁荣。

承蒙平素对DAIHEN无尘搬运机器人及等离子发生高周波/微波电源设备的特别惠顾，诚挚谢意！

我们将于2017年3月14日~17日在上海新国际博览中心参加FPD China 2017，今年我们仍将带来最高端的技术和设备，敬请一定前来参观指导。

现如今，达谊恒集团作为而向无尘搬运机器人，以及焊接机在内工业机器人的集生产，销售为一体的综合厂商已经在中国扎根，并致力于为制造业提供完善的服务。

在今年的展会上，我们还将推出而向医学药品领域开发的医药搬运机器人FDCL-V4M，搭载DD马达的真空机器人UTV-DD4000，以及伯努力吸附式真空机器人UTX-RF5500RP，为了满足新领域客户的要求，我们的事业也在不断推进。

请务必莅临我司展台感受面向新次元的解决方案。

敬上



UTV-DD4000



UTX-RF5500RP



FDCL-V4M

Booth NO: W1-1301

SEMICON China 2017 Exhibitors List

Company

Company	Booth Hall	Company	Booth Hall
<LED DISPLAY>	T812	Beijing Sinodynetest Science&Technology Co.,Ltd	4149
3D-Micromac AG	2549-4	Beijing Tian Neng Yun Tong Crystal Technique Co.,Ltd.	4237
3S (Shanghai) Co., Ltd.	2667	Beijing Xiantec Technology Ltd.	5455
A ABM, Inc	3267	Beijing Zhongke Holding Co., Ltd	4229
AccoTEST Business Unit of Beijing Huafeng Test & Control Technology Co.,Ltd.	3135	Bengbu Bright Semiconductor Co., Ltd	2463
Achilles Corporation	3363	Besi (BE) Semiconductor Industries N.V.)	4617
ACM Research (Shanghai), Inc.	5659	Bestac Advanced Material Co., Ltd	2816
ACOULAB Co., Ltd.	3154	Betone Technology (Shanghai),Inc.	5655
ADAMANT Co., Ltd	4771	Boffotto Ltd	2176
Adelis Associates Pte Ltd.	5677	Bohong Precision Machinery Manufacture (Wuxi) Co., Ltd	4326
Advance Process Technology, Inc.	5554	Böl Opt Sdn Bhd	1753
Advanced Dicing Technologies Ltd	3259	Boschman Technologies B.V.	3363
Advanced Energy Industries, Inc., Shanghai	3643	Broadway Precision Technology Co., Ltd	1226
Advanced Global Alliance Limited	3163	Brooks Automation, Inc.	3233
Advanced Technology&Materials Co.,Ltd	1601	Bubbles & Beyond GmbH	3022
Advantek Electronic Packaging (Shanghai) Co., Ltd.	2156	Bueno Technology Co., Ltd.	3126
Advantest (China) Co., Ltd.	4428	Bukwang Tech Co., Ltd.	1633
AGC Instruments	5377	C &D Semiconductor Services, Inc.	5335
AGVA Technologies Pte Ltd	4176	Cabot Microelectronics Corporation	3111
AI Technology, Inc.	1514	Camfil Filtration (Kunshan) Co., Ltd	2109
Air Bearings Ltd	3376	Camtek HK Ltd.	4114
Air Liquide Shanghai Co., Ltd.	5101	Canon Machinery Inc.	4359
Air Products and Chemicals (China)	1137	Carl Zeiss Far East Co., Ltd.	2022
Akrilis Systems (Shanghai) Co.,Ltd	3119	Cascade Microtech	2343
Allied Supreme (Jia Xing) Corp.	4800	Centrotherm clean solutions GmbH & Co. KG	3601
Allround Trading (Shanghai) CO., Ltd.	3639	Century 3 (Shanghai) Inc.	7329
Alltek Company	3353-1	CETC Electronics Equipment Group Co., LTD	3463
Allwin21 Corporation	3775	Chain Logic (Shanghai) International Corp.	4143-1
ALPHA PLASMA Vertrieb Plasma Systeme	2310	ChangChun GuangHua Micro-Electronics Equipment	4317
AM Technology Co., Ltd	T230	Engineering Center Co., Ltd.	W4
American Tec Co. Ltd	4167	Changsha DIAT New Material Sci. & Tech. Co., Ltd.	1519
AMFLO Fluid System & Components Co., Ltd.	3116	Changshu Aufirst Optoelectronic Materials Co., Ltd	1735
Anhui Argosun New Electronic Material Co.,Ltd.	1539	Changzhou Changyao	1675
Anji Microelectronics (Shanghai) Co.,Ltd.	5359	Changzhou Ruize Microelectronics Co., Ltd	2313
ANZ Company	3277	Changzhou Tianlong Optoelectronic Equipment Co.,Ltd	2371
AP&S International GmbH	2316	Chart Automation System Co., Ltd	5000
APIC YAMADA CORPORATION	4824	ChemTrace, A Quantum Global Technologies, LLC	5776
Applied Microengineering Ltd. (AML)	5335	Company	W5
Applied Nano Technology Science, Inc.	1751	Cheng Tay Heater & Instrument Co., Ltd	3749
Asahi Diamond Industrial Co., Ltd.	1623	Chengdu ArTech Specialite Graphite Co., Ltd	2808
ASAHI YUKIZAI CORPORATION	2745	Chengdu Laipu Science & Technology Co., Ltd	2181
ASE Group	5417	Chengdu Shangming Industrial Co., Ltd	2604
ASFLOW Co., Ltd.	2828	Chengdu Yeheng Electronic Co., Ltd	3771
ASM Technology Singapore Pte. Ltd.	4437	China Electronic Market	T808
Astronics Test Systems	2115	China Electronic Production Equipment Industry	4127
ATI Korea Co., Ltd.	5314	Association	W4
Atlas Copco (Shanghai) Trading Co., Ltd	1532	China Electronics Chamber of Commerce	T804
Atlas Technology Corporation	4576	China Electronics Materials Industry Association	T800
Atotech (China) Chemicals Ltd.	5363	China Electronics System Engineering No.2	2567
ATT Systems GmbH	2201	Construction Co.,Ltd	W2
AUROS Technology, Inc.	5205	China Electronics Technology Group Corporation	2559
B Baoding North Special Gas Co., Ltd	1816	No.46 Research Institute	W2
Baud Technology Shanghai Co., Ltd.	4631	China Integrated Circuit	T813
BCnC CO., LTD	5581	China Semiconductor Industry Association	T1
Be First Technology Co., Ltd.	4543	China Silicon Corporation Ltd.	T129
Beckhoff Automation (Shanghai) Co., Ltd	3579	China Wafer Level CSP Co., Ltd	5014
BECS Co., Ltd	1736	Chongqing Advanced Silicon Technology Co., Ltd.	5639
Beijing Asia Science & Technology Co., Ltd	5563	Chroma ATE Inc.	3635
Beijing BBEF Science&Technology Co., Ltd.	2749	CHUKOH Chemical (Shanghai) Trading., Ltd	1637
Beijing Beiyi Innovation Vacuum Technology Co., Ltd	4139	Chung King Enterprise Co.,Ltd	2163
Beijing Beyond Vacuum Technology Co., Ltd	2154	CHYI DING Technologies Co., Ltd.	5806
Beijing CGB Technology Co., Ltd	2439	Cimetrix Inc	2552
Beijing Chr-top Optical-Electronic Technology Co., Ltd.	2449	CIS Corporation	5366
Beijing DoubleLink Solders Co., Ltd.	4745	CKD Corporation	5643
Beijing Grish Hitech Co., Ltd.	2432	CN1 Co., Ltd	T116
Beijing He Qi Precision Technology Inc.	2639	CND PLUS	5217
Beijing Jingyi Automation Equipment Co., Ltd	3651	Cobham Wireless (formerly Aeroflex)	4709
Beijing Kaide Quartz Corporation	2101	CohPros International Co., Ltd	2563
BEIJING KONGLIAN CNC Technology Co., Ltd.	4213	COMET Mechanical Equipment (Shanghai) Co. Ltd.	2537
Beijing Lixin Test Technology Co., Ltd	2726	Compound Semiconductors China	2810
Beijing Longsun Technology Co., Ltd.	2457	Conax Technologies LLC	2150
Beijing Mobile E-TOWN Co., Ltd	5623	CONNECTEC JAPAN Corporation	1528
Beijing NAURA Microelectronics Equipment Co.,Ltd.	3243	CoorsTek Trading (Shanghai) Co., Ltd	3143
Beijing Oriental Jicheng Co.,Ltd	1705	Corad Technology, Ltd.	4477
Beijing Reje Automation Co., Ltd	1605		W4
Beijing SinLeader	2219		

展馆平面图 Hall W1



展馆平面图 Hall W2



展馆平面图 Hall W3



展馆平面图 Hall W4



展馆平面图 Hall W5



中国国际半导体技术大会(CSTIC) 2017
China Semiconductor Technology
International Conference (CSTIC) 2017

日期Date: 2017年3月12日–13日 March 12–13, 2017

地点Venue: 上海国际会议中心 Shanghai International Convention Center



Prof. Hiroshi Amano
Nobel Laureate in
Physics, 2014
Director, Center for
Integrated Research of
Future Electronics,
Institute of Materials and
Systems for Sustainabilili-
ty, Nagoya University



Dr. Tzu-Yin Chiu
CEO and Executive
Director, Semiconductor
Manufacturing
International Corp.
(SMIC)



Dr. Jong Shik Yoon
Executive Vice President
Foundry Business
System-LSI, Samsung
Electronics Co., LTD, Ko-
rea



Prof. Rao Tummala
Joseph M. Pettit Chair
Professor in ECE and MSE
Director, 3D Microsystems
Packaging Research
Center, Georgia Research
Alliance Eminent Scholar
Georgia Institute of
Technology, Atlanta, Ga, USA

Topics to be addressed at CSTIC 2017 include, but not limited to the following:

Symposium I: Device Engineering and Memory Technology

Symposium II: Lithography and Patterning

Symposium III: Dry & Wet Etch and Cleaning

Symposium IV: Thin Film, Plating and Process Integration

Symposium V: CMP and Post-Polish Cleaning

Symposium VI: Metrology, Reliability and Testing

Symposium VII: Packaging and Assembly

Symposium VIII: MEMS, Sensors and Emerging Semiconductor Technologies

Symposium IX: Circuit Design, Systems and Applications

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